RECOMMENDED PCB LAYOUT FOR TFC-1XX-XX-D-XX AND TFM-1XX-X2-XXX-D-XX



REVISION P

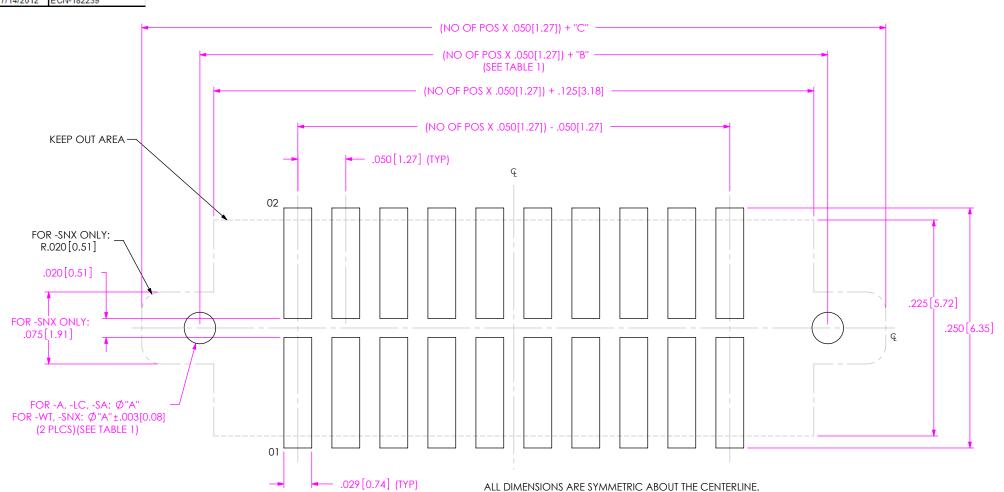


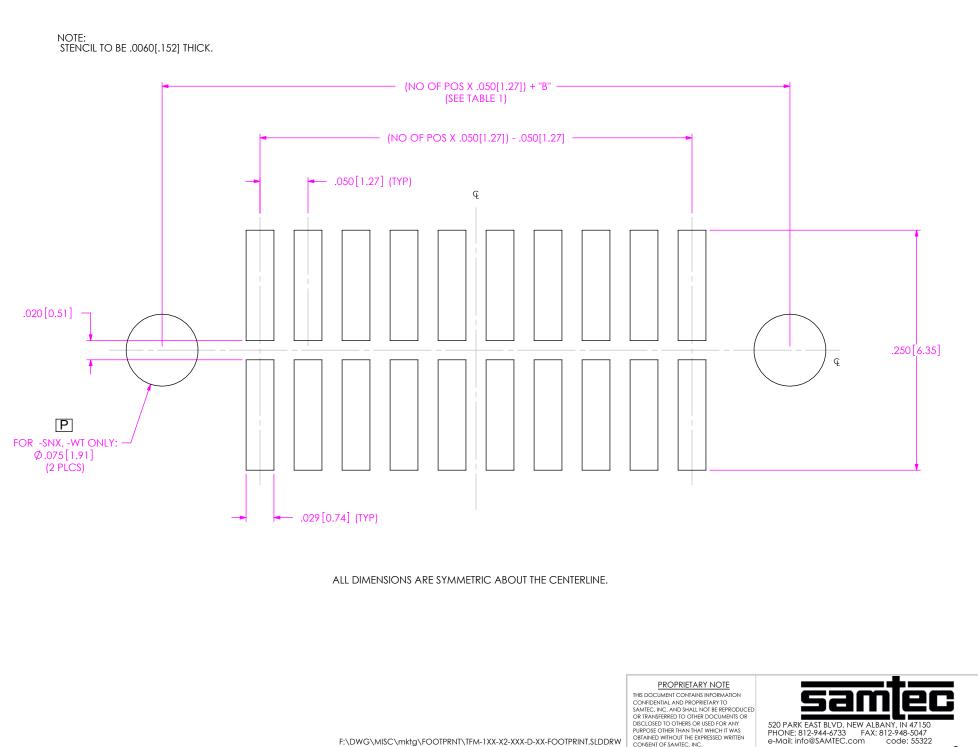
	TABLE 1						
	OPTION	"A"		"B"		"C"	
	-A	.056	[1.42] NPTH	.075	[1.91]	.125	[3.18]
	-LC	.047	[1.19] NPTH	.075	[1.91]	.125	[3.18]
	-SA	.038	[0.97] NPTH	.075	[1.91]	.125	[3.18]
	-WT (TO BE SOLDERED USING PA STE-IN-HOLE TECHNOLOGY)	. 0 33	[0.84] PTH	.154	[3.91]	.263	[6.68]
	-SNX (TO BE SOLDERED USING PA STE-IN-HOLE TECHNOLOGY)	.033	[0.84] PTH	.175	[4.45]	.275	[6.99]
Ρ	-DS	.055	[1.40] NPTH	.075	[1.91]	.600	[15.24]

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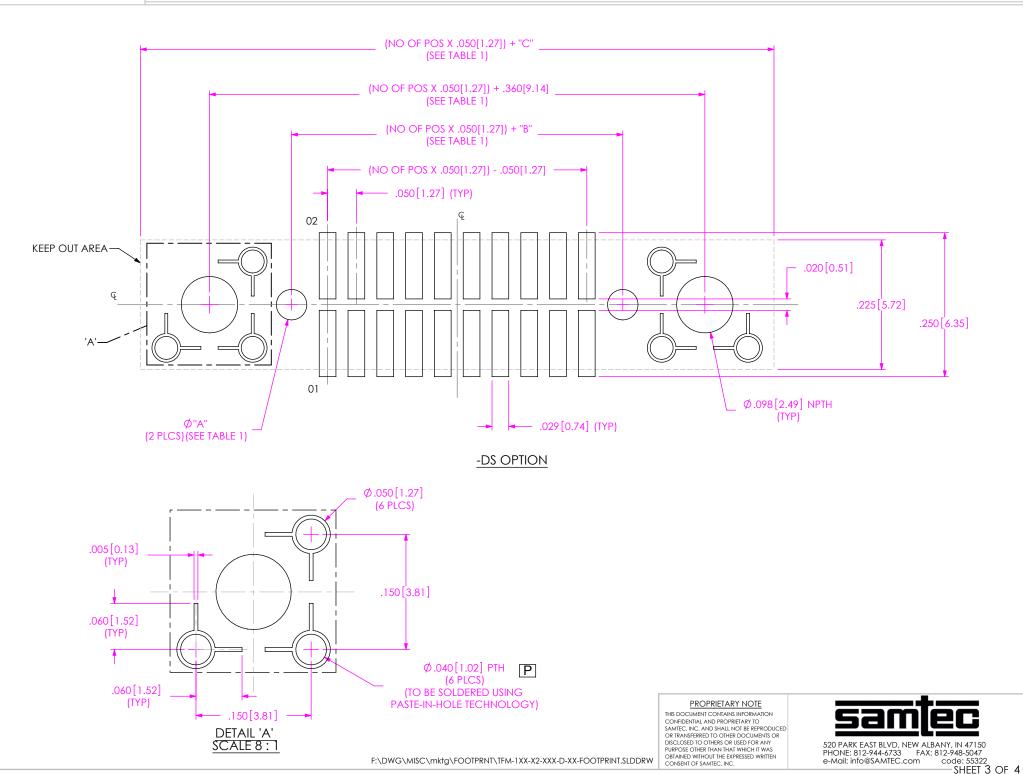
F:\DWG\MISC\mktg\FOOTPRNT\TFM-1XX-X2-XXX-D-XX-FOOTPRINT.SLDDRW

REVISION P RECOMMENDED STENCIL LAYOUT FOR TFC-1XX-XX-D-XX AND TFM-1XX-X2-XXX-D-XX



REVISION P

RECOMMENDED PCB LAYOUT FOR TFM-1XX-X2-XXX-D-DS



REVISION P

RECOMMENDED STENCIL LAYOUT FOR TFM-1XX-X2-XXX-D-XX

